# Product Change Notification: CENO-24XLXZ077

## Date:

29-Sep-2026

## Product Category:

16-Bit Microcontrollers, Digital Signal Controllers

## Notification Subject:

CCB 8542 Final Notice: Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102 device families available in 28L SSOP (.209in) package.

## Affected CPNs:

**CENO-24XLXZ077_Affected_CPN_09292026.pdf**
**CENO-24XLXZ077_Affected_CPN_09292026.csv**

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102 device families available in 28L SSOP (.209in) package.

**Pre and Post Summary Changes**:

| | **Pre Change** | **Post Change** | | **Change** |
|---|---|---|---|---|
| Assembly Site | Amkor Technology Philippine (P1/P2), | Amkor Technology Philippine (P1/P2), | Microchip Technology | Yes |

| | INC. (ANAP) | INC. (ANAP) | Thailand (HQ) (MTAI) | |
|---|---|---|---|---|
| Wire Material | Au | Au | Au | No |
| Die Attach Material | 8290 (PFAS) | 8290 (PFAS) | QMI519 (PFAS-free) | Yes |
| Molding Compound Material | G600 | G600 | G600 | No |
| Lead-Frame Material | CDA194 | CDA194 | CDA194 | No |
| Lead-Frame Paddle Size | 154 x 200 mils | 154 x 200 mils | 153 x 200 mils | Yes |
| Lead-Frame DAP Surface Prep | Ag ring plate | Ag ring plate | Ag selective | Yes |
| Lead-Frame Drawing | See Pre and Post Change Summary Attachment for Comparison. | | | |

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 20 November 2026 (date code: 2647)

**Note Below EFSD:** Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary**:

| | September 2026 | | | | | > | November 2026 | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| Work Week | 36 | 37 | 38 | 39 | 40 | | 45 | 46 | 47 | 48 |
| Qual Report Availability | | | | | x | | | | | |
| Final PCN Issue Date | | | | | x | | | | | |

| | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| Estimated Implementation Date | | | | | | | | | x | |

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.
Note: This is a qualification by similarity (QBS) to CCBs# 3839 and 8090.

**Revision History:** September 29, 2026: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

## Attachments:

**PCN_CENO-24XLXZ077 Pre and Post Change Summary.pdf**
**PFAS Elimination and Die Attach_Explanation.pdf**
**PCN_CENO-24XLXZ077 Qual Report-CCB 3839.pdf**
**PCN_CENO-24XLXZ077 Qual Report-CCB 8090.pdf**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CENO-24XLXZ077 - CCB 8542 Final Notice: Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102

Affected Catalog Part Numbers (CPN):

DSPIC33EP32MC202T-E/SS

DSPIC33EP32GP502-I/SS

DSPIC33EP32MC502-I/SS

PIC24EP32GP202-I/SS

DSPIC33EP32MC202T-I/SS

DSPIC33EP64GP502-E/SS

DSPIC33EP64GP502-E/SSVAO

DSPIC33EP64GP502T-E/SSVAO

DSPIC33EP64MC502T-E/SS

DSPIC33EP64MC202-E/SSVAO

PIC24EP64GP202-I/SS

PIC24EP64GP202T-I/SS

DSPIC33EP64MC202T-E/SSC05

DSPIC33EP64MC502-I/SS

PIC24EP64MC202-E/SS

DSPIC33EP64MC202T-I/SS

PIC24EP64MC202T-E/SS

DSPIC33EP32GP502-I/SSVAO

DSPIC33EP32GP502T-I/SSVAO

DSPIC33EP32MC202T-H/SSVAO

DSPIC33EP32MC202-E/SSVAO

DSPIC33EP32MC202T-E/SSVAO

DSPIC33EP32GP502T-I/SS

DSPIC33EP32GP502T-E/SS

PIC24FJ64GB002-I/SS

PIC24FJ64GB002T-I/SS

PIC24FJ32GB002-I/SS

PIC24FJ32GA102T-I/SS

PIC24FJ32GA102-I/SS

PIC24FJ64GA102-I/SS

PIC24FJ32GA102-E/SS

DSPIC33EP64MC502T-I/SS

DSPIC33EP64MC202-I/SS

DSPIC33EP64MC202-E/SS

DSPIC33EP64GP502-I/SS

PIC24EP64MC202-I/SS

DSPIC33EP64MC202T-E/SS

PIC24EP64MC202T-I/SS

DSPIC33EP64MC502-E/SS

DSPIC33EP64GP502T-I/SS

DSPIC33EP32GP502T-E/SSVAO

DSPIC33EP32GP502-E/SSVAO

DSPIC33EP32MC502T-E/SSVAO

DSPIC33EP32MC502-E/SSVAO

DSPIC33EP32MC202-H/SSVAO

PIC24EP32GP202-E/SS

PIC24EP32MC202-E/SS

DSPIC33EP32MC502-E/SS

PIC24EP32GP202T-I/SS

PIC24EP32MC202T-E/SS

PIC24EP32GP202T-E/SS

DSPIC33EP32MC502T-E/SS

PIC24EP32MC202-I/SS

DSPIC33EP32GP502-E/SS

DSPIC33EP32MC202-E/SS

DSPIC33EP32MC202-I/SS

# CCB 8542
# Pre and Post Change Summary
# PCN#: CENO-24XLXZ077

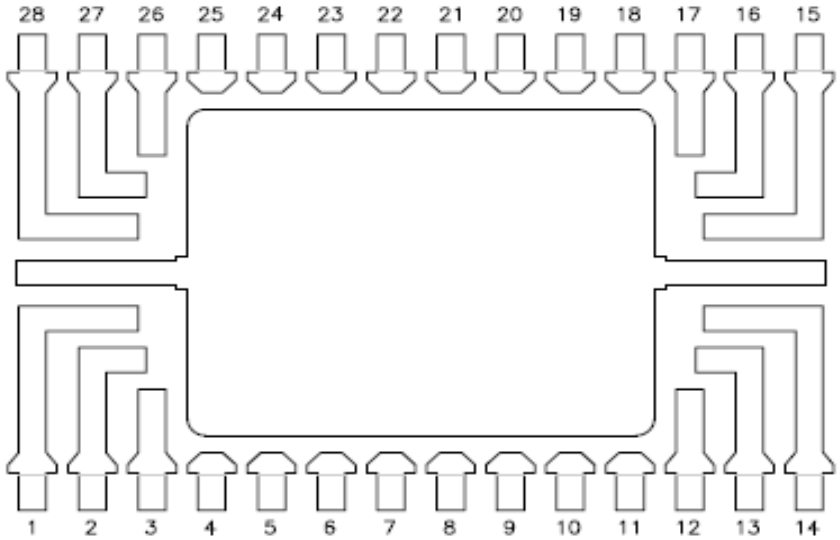



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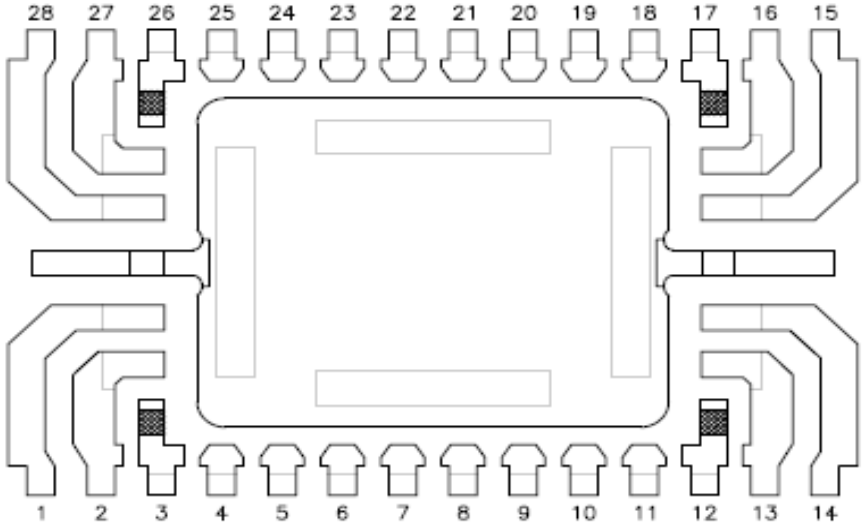
# Lead Frame Comparison

## ANAP




| LF Paddle size | 154 x 200 mils |
|---|---|

## MTAI




| LF Paddle size | 153 x 200 mils |
|---|---|

*Note: Not to scale.*

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# Qualification Report Summary

## RELIABILITY LABORATORY

## PCN #: CENO-24XLXZ077

**Date**

**Nov 21, 2019**

**Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102 device families available in 28L SSOP (.209in) package. This is a Q100 Grade 0 qualification.**

# PACKAGE QUALIFICATION REPORT

**Purpose:**

Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102 device families available in 28L SSOP (.209in) package. This is Q100 Grade 0 qualification.

| | |
|---|---|
| **CN:** | ES311349 |
| **QUAL ID:** | Q19123 |
| **QUAL ID Rev.:** | A |
| **MP CODE:** | TLAC14N2XVL1 |
| **Part No.:** | DSPIC33EP64GP502-E/SSVAO |
| **Bonding No.:** | BDM-001885 Rev. D |
| **CCB No.:** | 3839 |

## Lead Frame

| | |
|---|---|
| **Paddle Size:** | 153 x 200 mils |
| **Material:** | CDA194 |
| **DAP Surface Prep:** | Bare Cu with BOT selective Ag |
| **Process:** | Stamp |
| **Lead Lock:** | No |
| **Part Number:** | 10102838 |
| **Lead Plating:** | Matte Tin |

## Bond Wire

| | |
|---|---|
| **Wire:** | Au wire |

## Die Attach Material

| | |
|---|---|
| **Epoxy:** | 3280 |

## Mold Compound

| | |
|---|---|
| **Mold Compound:** | G600 |

## Package

| | |
|---|---|
| **Type:** | 28L SSOP |
| **Package Size:** | 209 In |

## Manufacturing Information

| Assembly Lot No. | Wafer Lot No. | Date Code |
|---|---|---|
| MTAI200901609.000 | TC11920054471.200 | 1922TEW |
| MTAI200901610.000 | TC11920054471.200 | 1922TEY |
| MTAI200902186.000 | TC11920054471.200 | 1922UVS |

Result: **Pass**

## Conclusion:

28L SSOP assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

# PACKAGE QUALIFICATION REPORT

| Test Number (Reference) | Test Condition | Standard/ Method | Qty. (Acc.) | Def/SS. | Result | Remarks |
|---|---|---|---|---|---|---|
| | **Electrical Test :**+25°C, 85°C ,125°C and 150°C<br>**System:** J750 | JESD22-A113 | 693(0) | 693 | | Good Devices |
| | Bake 150°C, 24 hrs<br>**System:** CHINEE | JIP/IPC/JEDEC J-STD-020E | | 693 | | |
| **Precondition Prior Perform Reliability Tests (At MSL Level 1)** | 85°C/85%RH Moisture Soak 168 hrs.<br>**System:** TABAI ESPEC Model PR-3SPH | | | 693 | | |
| | 3x Convection-Reflow 265°C max<br>**System:** Vitronics Soltec MR1243 | | | 693 | | |
| | **Electrical Test :**+25°C, 85°C ,125°C and 150°C<br>**System:** J750 | | | 0/693 | Pass | |
| | **Stress Condition:**<br>-55°C to +150°C, 1000 Cycles | JESD22-A104 | 231(0) | 231 | | Parts had been pre-conditioned at 260°C |
| | **Electrical Test:** +85°C ,125°C and 150°C<br>**System:** J750 | | | 0/231 | Pass | 77 units / lot |
| **Temp Cycle** | **Stress Condition:**<br>-55°C to +150°C, 2000 Cycles | | 231(0) | 231 | | |
| | **Electrical Test:** +85°C ,125°C and 150°C<br>**System:** J750 | | | 0/231 | Pass | |
| | **Bond Strength:**<br>Wire Pull (> 3.00 grams) | | 15(0) | 0/15 | Pass | |
| | Bond Shear (>18.00 grams) | | 15(0) | 0/15 | Pass | |
| **UNBIASED-HAST** | **Stress Condition:**<br>+130°C/85%RH, 96 hrs.<br>**System:** HAST 6000X | JESD22-A118 | 231(0) | 231 | | Parts had been pre-conditioned at 260°C |
| | **Electrical Test:** +25°C<br>**System:** J750 | | | 0/231 | Pass | 77 units / lot |

# PACKAGE QUALIFICATION REPORT

| Test Number (Reference) | Test Condition | Standard/ Method | Qty. (Acc.) | Def/SS. | Result | Remarks |
|---|---|---|---|---|---|---|
| **HAST** | **Stress Condition:** +130°C/85%RH, 96 hrs. Bias Volt: 3.6 Volts **System:** HAST 6000X | JESD22-A110 | 231(0) | 231 | | Parts had been pre-conditioned at 260°C |
| | **Electrical Test :**+25°C, 85°C ,125°C and 150°C **System:** J750 | | | 0/231 | Pass | 77 units / lot |
| **High Temperature Storage Life** | **Stress Condition:** Bake 175°C, 500 hrs | JESD22-A103 | 45(0) | 45 | | 45 units |
| | **Electrical Test :**+25°C, 85°C ,125°C and 150°C **System:** J750 | | | 0/45 | Pass | |
| | **Stress Condition:** Bake 175°C, 1000 hrs | | 45(0) | 45 | | |
| | **Electrical Test :**+25°C, 85°C ,125°C and 150°C **System:** J750 | | | 0/45 | Pass | |
| **Bond Strength Data Assembly** | Wire Pull (> 3.00 grams) | M2011 | 30(0) | 0/30 | Pass | |
| | Bond Shear (>18.00 grams) | JESD22-B116 | 30(0) | 0/30 | Pass | |



# Qualification Report Summary

## RELIABILITY LABORATORY

## PCN #: CENO-24XLXZ077

**Date**

**August 24, 2026**

**Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102 device families available in 28L SSOP (.209in) package.**

# PACKAGE QUALIFICATION REPORT

**Purpose:**

Qualification of MTAI as an additional assembly site for selected PIC24EP64MC202, dsPIC33EP64MC202, dsPIC33EP64MC502, dsPIC33EP64GP502, PIC24EP64GP202, dsPIC33EP32MC202, dsPIC33EP32GP502, dsPIC33EP32MC502, PIC24EP32GP202, PIC24EP32MC202, PIC24FJ64GB002, PIC24FJ32GB002, PIC24FJ32GA102 and PIC24FJ64GA102 device families available in 28L SSOP (.209in) package.

| | |
|---|---|
| **QUAL ID:** | R2600543 |
| **QUAL ID Rev.:** | A |
| **MP CODE:** | TLAE1MN2XPFA |
| **Part No.:** | PIC24EP256MC202-H/SS |
| **Bonding No.:** | BD-0014173 Rev 01 |
| **CCB No.:** | 8090 |

## Lead Frame

| | |
|---|---|
| **Paddle Size:** | 153 x 200 mils |
| **Material:** | CDA194 |
| **DAP Surface Prep:** | Bare Cu |
| **Process:** | Stamped |
| **Lead Lock:** | No |
| **Part Number:** | 10102834 |
| **Lead Plating:** | Matte Tin |

## Bond Wire

| | |
|---|---|
| **Wire:** | CuPdAu |

## Die Attach Material

| | |
|---|---|
| **Epoxy:** | QMI519 |
| **Conductive:** | Yes |

## Mold Compound

| | |
|---|---|
| **Mold Compound:** | G600 |

## Package

| | |
|---|---|
| **Type:** | SSOP |
| **Package Size:** | 209 mils |

# PACKAGE QUALIFICATION REPORT

## Manufacturing Information

| Assembly Lot No. |
|---|
| MTAI270401828.000 |
| MTAI270401829.000 |
| MTAI270500002.000 |

Result: **Pass**

Conclusion:
Qualification of TLAE1 mask / PIC24EP256MC202-H/SS product / CuPdAu wire in 28L SSOP 209 mils package at MTAI site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

# PACKAGE QUALIFICATION REPORT

| Test Number (Reference) | Test Condition | Standard/ Method | Qty. (Acc.) | Def/SS. | Result | Remarks |
|---|---|---|---|---|---|---|
| **Precondition (Moisture Soak)** | **MSL1:** 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C<br>**Electrical Test:** 25°C, 85°C, 125°C and 150°C<br>**Tester:** J750 | JESD22-A113 , JEDEC J-STD-020 | 693(0) | 0/693 | Pass | |
| **High Temperature Storage Life (HTSL)** | 175°C / 1000 hours<br>**Electrical Test:** 25°C, 85°C, 125°C and 150°C<br>**Tester:** J750 | JESD22-A103 | 135(0) | 0/135 | Pass | Electrical Results |
| | | | 9(0) | 0/9 | Pass | WBP |
| | | | 9(0) | 0/9 | Pass | WBS |
| **Temperature Cycling** | -55°C / +150°C Air to Air / 1500 Cycles<br>**Electrical Test:** 25°C, 85°C, 125°C and 150°C<br>**Tester:** J750 | JESD22-A104 | 231(0) | 0/231 | Pass | Electrical Results |
| | | | 9(0) | 0/9 | Pass | WBP |
| | | | 9(0) | 0/9 | Pass | WBS |
| **Biased HAST** | +130°C / 85%RH / 96 hours / Bias Voltage: 3.6V<br>**Electrical Test:** 25°C, 85°C, 125°C and 150°C<br>**Tester:** J750 | JESD22-A110 | 231(0) | 0/231 | Pass | Electrical Results |
| | | | 9(0) | 0/9 | Pass | WBP |
| | | | 9(0) | 0/9 | Pass | WBS |
| **Unbiased HAST** | +130°C / 85%RH / 96 hours<br>**Electrical Test:** 25°C<br>**Tester:** J750 | JESD22-A118 | 231(0) | 0/231 | Pass | |
| **Solderability (0 Hr) Method 1: Dip and Look** | Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage | J-STD-002 / JESD22B-102 | 22(0) | 0/22 | Pass | |
| **Physical Dimension (0Hr)** | Within package diagram dimension | JESD22 B100 and B108 | 30(0) | 0/30 | Pass | |
| **Wire Pull** | Bond Strength Data Assembly | Mil. Std. 883-2011 | 5(0) | 0/5 | Pass | |

# PACKAGE QUALIFICATION REPORT

| Test Number (Reference) | Test Condition | Standard/ Method | Qty. (Acc.) | Def/SS. | Result | Remarks |
|---|---|---|---|---|---|---|
| **Bond Shear** | Bond Strength Data Assembly | CDF-AEC-Q100-001 | 5(0) | 0/5 | Pass | |

# Eliminating PFAS from Microchip ICs




A Leading Provider of Smart, Connected and Secure Embedded Control Solutions




**Microchip**

August 2025

# Eliminating PFAS from MCHP ICs

- What is PFAS
- Microchip's Environmental Stewardship
- Microchip Products with PFAS
- Time Frame to PFAS-Free Die Attach
- What is Die Attach
- Will clients be required to switch to PFAS free products
- Risk Assessment

# What is PFAS: Poly(Per) FluoroAlkyl Substances (PFAS)

## Poly(Per) FluoroAlkyl Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
  - PFAS can be in the product itself.
  - PFAS can also be used to manufacture products while not in the product itself

## PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet



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# Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

**Achieving "PFAS-Free" status may serve as a competitive advantage for both Microchip and its clients.**

# Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

# Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

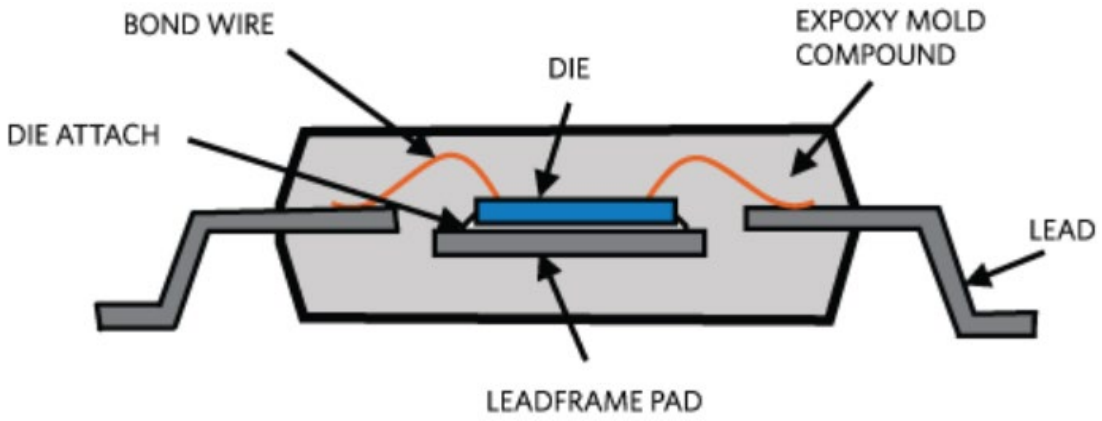
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

# What is die attach




**A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.**

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**



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# Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

# Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

**Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.**





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